

225mW SMD Switching Diode

FEATURES

- Low power loss, high current capability, low VF
- Surface mount device type
- Moisture sensitivity level 1
- Matte Tin (Sn) lead finish with Nickel (Ni) underplate
- Pb free version and RoHS compliant
- Packing code with suffix "G" means green compound (halogen-free)









MECHANICAL DATA

- Case: Bend lead SOT-23 small outline plastic package
- Terminal: Matte tin plated, lead free., solderable per MIL-STD-202, Method 208 guaranteed
- High temperature soldering guaranteed : 260°C/10s
- Weight: 8 ± 0.5 mgMarking Code: A6

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS (T _A =25°C unless otherwise noted)				
PARAMETER	SYMBOL	VALUE	UNIT	
Power dissipation	P _D	225	mW	
Repetitive peak reverse voltage	V_{RRM}	75	V	
Mean forward current	Io	150	mA	
Non-repetitive peak forward surge current @t = 0.001 s	I _{FSM}	2	А	
Thermal resistance (Junction to Ambient) (Not	e 1) R _{eJA}	375	°C/W	
Junction and storage temperature range	T _J , T _{STG}	-65 to +150	°C	

PARA	SYMBOL	MIN	MAX	UNIT	
Reverse breakdown voltage	I _R = 100 μA	$V_{(BR)}$	75	-	V
	I _F = 1.0 mA		-	0.715	
Facus and continue	$I_F = 10 \text{ mA}$	\ \ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\		0.855	٦ ,,
Forward voltage	$I_F = 50 \text{ mA}$	V _F		1.000	- V
	I _F = 150 mA			1.250	
Reverse leakage current V _R = 75 V		I _R	-	1	μA
Junction capacitance $V_R = 0 \text{ V}$, $f = 1.0 \text{ MHz}$		C _J	-	2.0	pF
Reverse recovery time (Note 2)		t _{rr}	_	3.0	ns

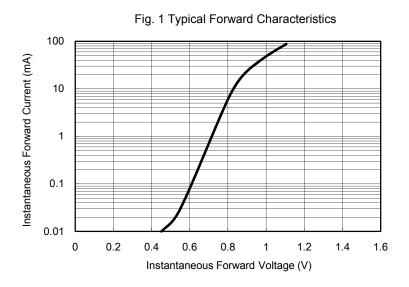
Note 1: Valid provided that electrodes are kept at ambient temperature

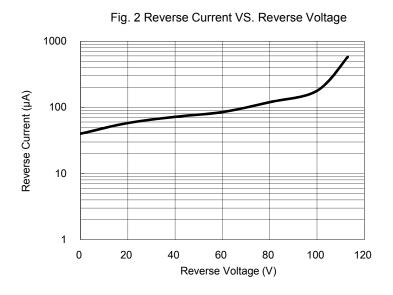
Note 2: Reverse recovery test conditions: $I_F \! = \! 10 \text{mA}$, $I_R \! = \! 10 \text{mA}$, $R_L \! = \! 100 \; \Omega, \; I_{RR} \! = \; 1 \text{mA}$

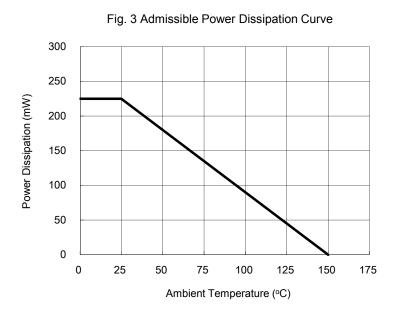


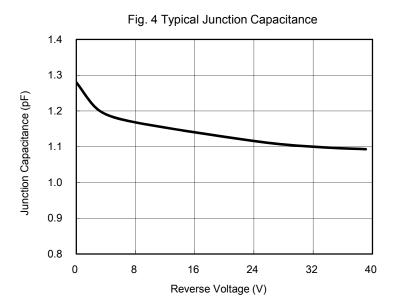
RATINGS AND CHARACTERISTICS CURVES

(T_A=25°C unless otherwise noted)









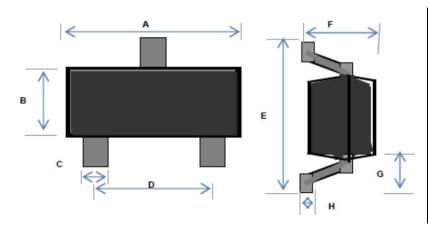


ORDERING INFORMATION					
PART NO.	PART NO. SUFFIX (Note 1)	PACKING CODE	PACKING CODE SUFFIX	PACKAGE	PACKING
BAS16	-XX	RF	G	SOT-23	3K / 7" Reel
-XX	R5	9	301-23	10K / 13" Reel	

Note 1: Part No. Suffix "-xx " would be used for special requirement

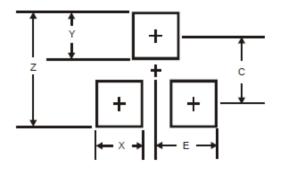
EXAMPLE					
PREFERRED P/N	PART NO.	PART NO. SUFFIX	PACKING CODE	PACKING CODE SUFFIX	DESCRIPTION
BAS16 RF	BAS16		RF		Multiple manufacture source
BAS16 RFG	BAS16		RF	G	Multiple manufacture source Green compound
BAS16-B0 RFG	BAS16	-B0	RF	G	Defined manufacture source Green compound

PACKAGE OUTLINE DIMENSIONS



DIM.	Unit (mm)		Unit (inch)	
DIIVI.	Min	Max	Min	Max
Α	2.70	3.10	0.106	0.122
В	1.10	1.50	0.043	0.059
С	0.30	0.51	0.012	0.020
D	1.78	2.04	0.070	0.080
E	2.10	2.64	0.083	0.104
F	0.89	1.30	0.035	0.051
G	0.55 REF		0.022	REF
Н	0.10 REF		0.004	REF

SUGGEST PAD LAYOUT



DIM.	Unit (mm)	Unit (inch)
DIIVI.	Тур.	Тур.
Z	2.8	0.110
Х	0.7	0.028
Υ	0.9	0.035
С	1.9	0.075
Е	1.0	0.039





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